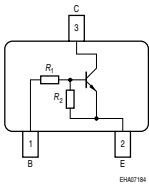
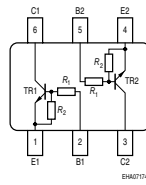


**NPN Silicon Digital Transistor**

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ( $R_1=22k\Omega$ ,  $R_2=22k\Omega$ )
- BCR141S / U: Two internally isolated transistors with good matching in one multichip package
- BCR141S / U: For orientation in reel see package information below


**BCR141/F/L3  
BCR141T/W**

**BCR141S/U**


Type	Marking	Pin Configuration						Package
		1=B	2=E	3=C	-	-	-	
BCR141	WDs	1=B	2=E	3=C	-	-	-	SOT23
BCR141F	WDs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR141L3	WD	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR141S	WDs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR141T	WD	1=B	2=E	3=C	-	-	-	SC75
BCR141U	WDs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74
BCR141W	WDs	1=B	2=E	3=C	-	-	-	SOT323

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	50	V
Collector-base voltage	$V_{CBO}$	50	
Input forward voltage	$V_{i(fwd)}$	60	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	$I_C$	100	mA
Total power dissipation- BCR141, $T_S \leq 102^\circ\text{C}$ BCR141F, $T_S \leq 128^\circ\text{C}$ BCR141L3, $T_S \leq 135^\circ\text{C}$ BCR141S, $T_S \leq 115^\circ\text{C}$ BCR141T, $T_S \leq 109^\circ\text{C}$ BCR141U, $T_S \leq 118^\circ\text{C}$ BCR141W, $T_S \leq 124^\circ\text{C}$	$P_{tot}$	200 250 250 250 250 250 250	mW
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-65 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$		K/W
BCR141		$\leq 240$	
BCR141F		$\leq 90$	
BCR141L3		$\leq 60$	
BCR141S		$\leq 140$	
BCR141T		$\leq 165$	
BCR141U		$\leq 133$	
BCR141W		$\leq 105$	

<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

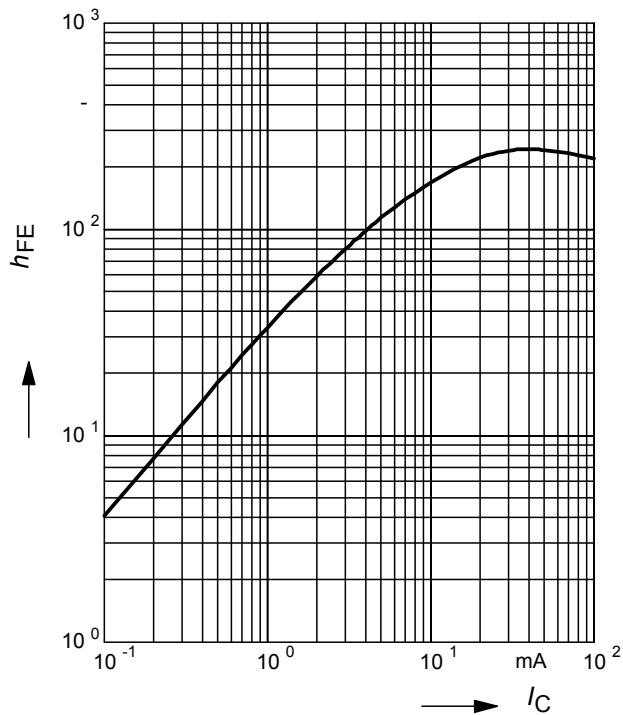
**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 10 \text{ V}, I_C = 0$	$I_{EBO}$	-	-	350	$\mu\text{A}$
DC current gain <sup>1)</sup> $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	$h_{FE}$	50	-	-	-
Collector-emitter saturation voltage <sup>1)</sup> $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	$V_{CEsat}$	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(off)}$	0.8	-	1.5	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(on)}$	1	-	2.5	
Input resistor	$R_1$	15	22	29	$\text{k}\Omega$
Resistor ratio	$R_1/R_2$	0.9	1	1.1	-
<b>AC Characteristics</b>					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	$f_T$	-	130	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	$C_{cb}$	-	3	-	pF

<sup>1</sup>Pulse test:  $t < 300 \mu\text{s}$ ;  $D < 2\%$

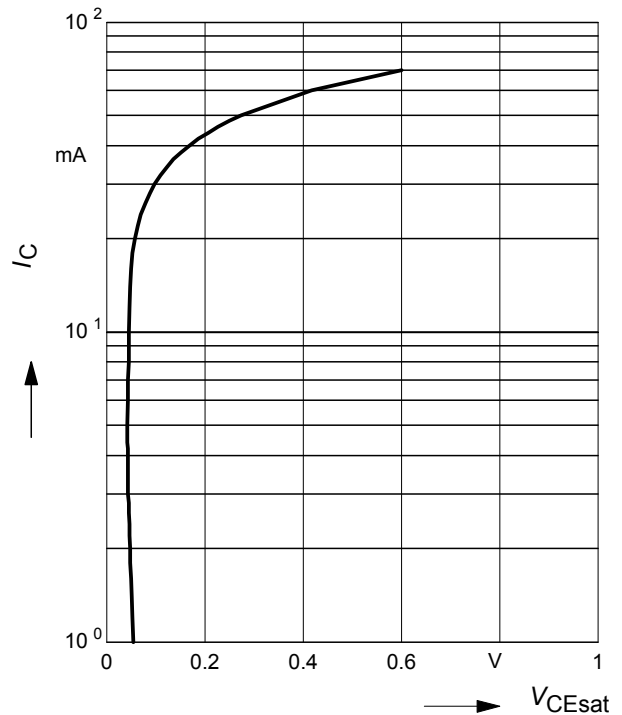
**DC current gain  $h_{FE} = f(I_C)$**

$V_{CE} = 5\text{ V}$  (common emitter configuration)



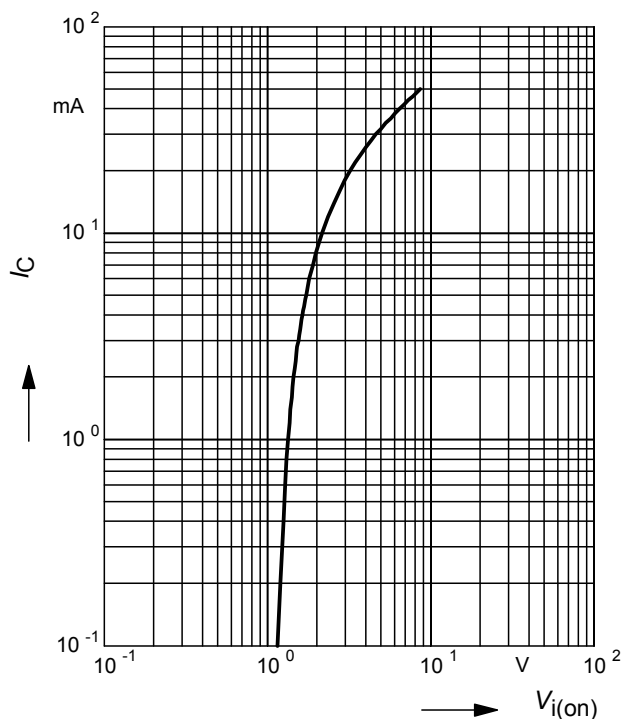
**Collector-emitter saturation voltage**

$V_{CEsat} = f(I_C), h_{FE} = 20$



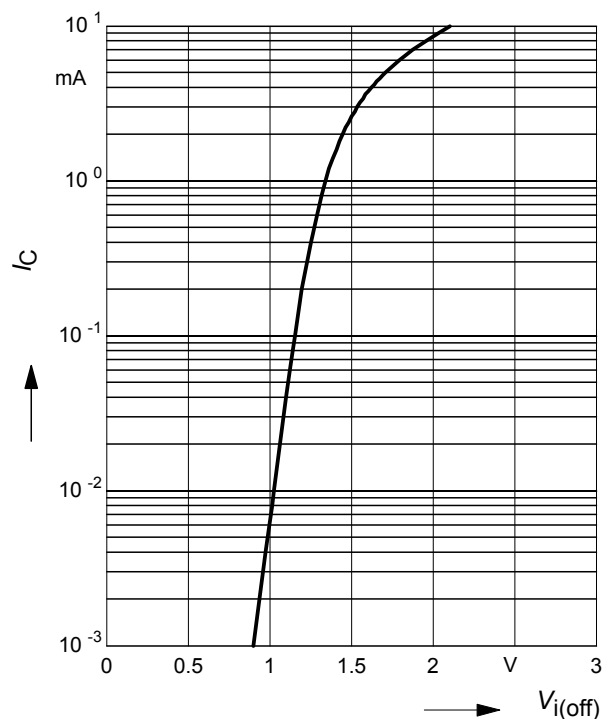
**Input on Voltage  $V_{i(on)} = f(I_C)$**

$V_{CE} = 0.3\text{ V}$  (common emitter voltage)



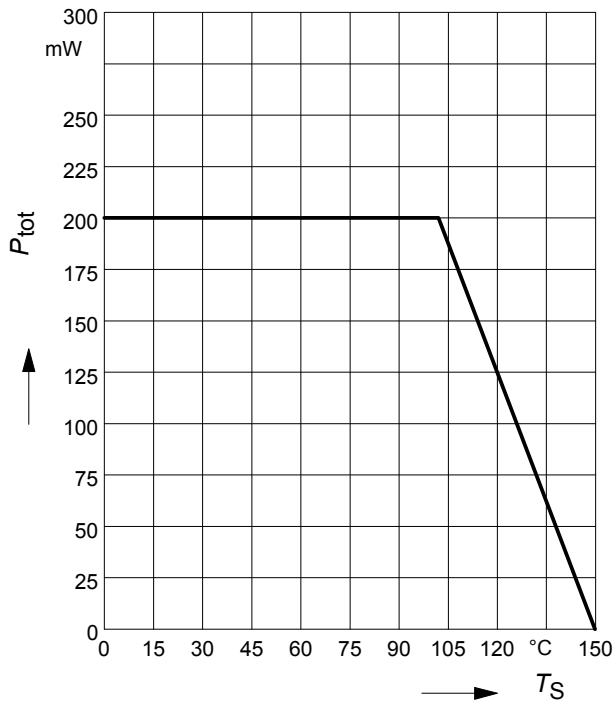
**Input off voltage  $V_{i(off)} = f(I_C)$**

$V_{CE} = 5\text{ V}$  (common emitter voltage)



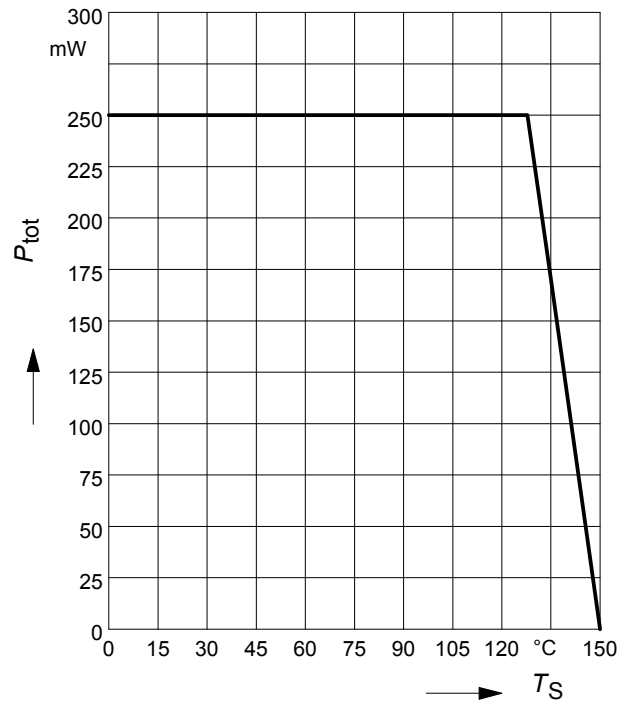
Total power dissipation  $P_{tot} = f(T_S)$

BCR141



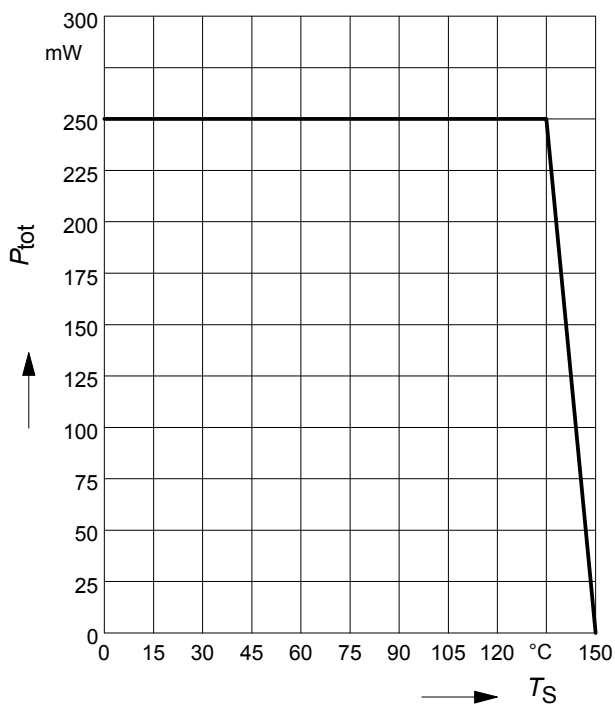
Total power dissipation  $P_{tot} = f(T_S)$

BCR141F



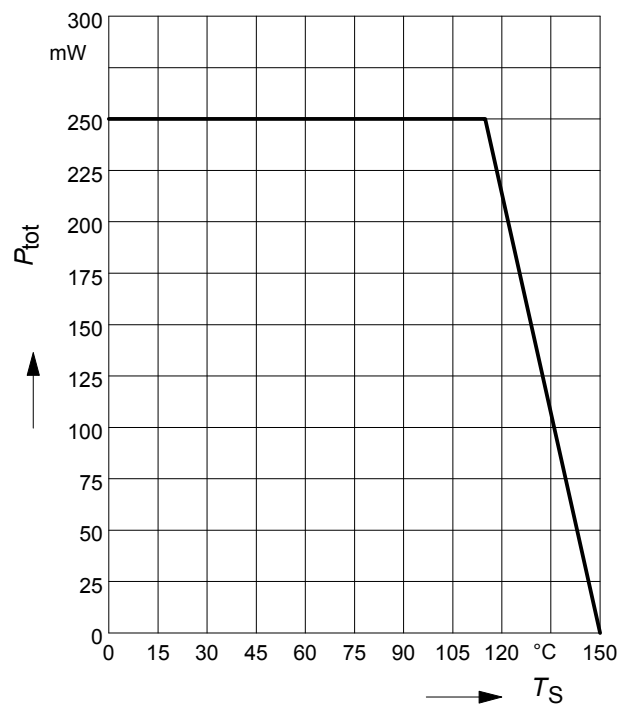
Total power dissipation  $P_{tot} = f(T_S)$

BCR141L3



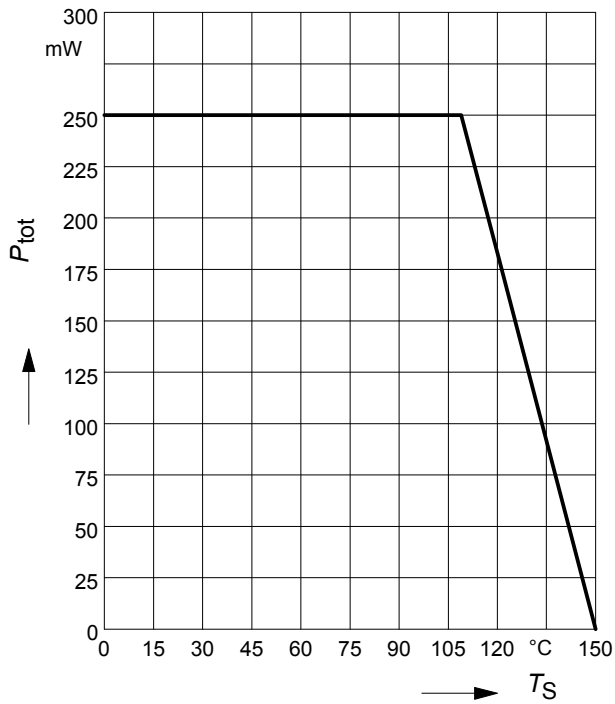
Total power dissipation  $P_{tot} = f(T_S)$

BCR141S



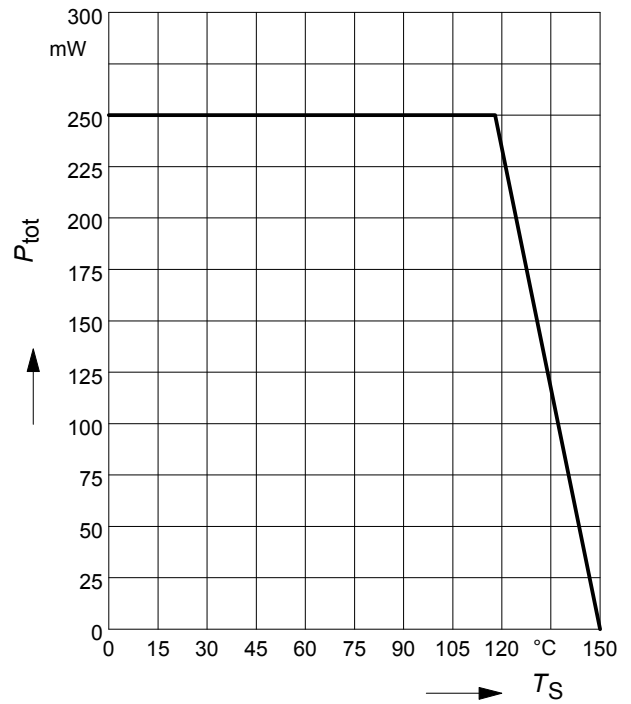
Total power dissipation  $P_{\text{tot}} = f(T_S)$

BCR141T



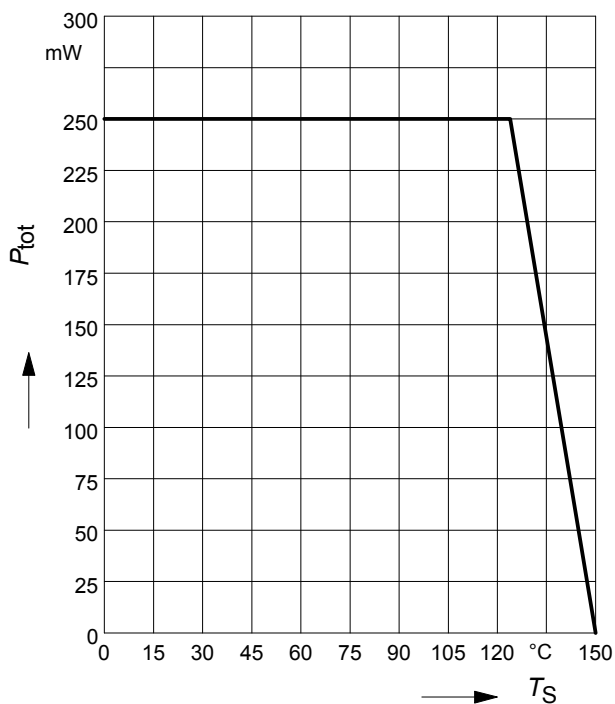
Total power dissipation  $P_{\text{tot}} = f(T_S)$

BCR141U



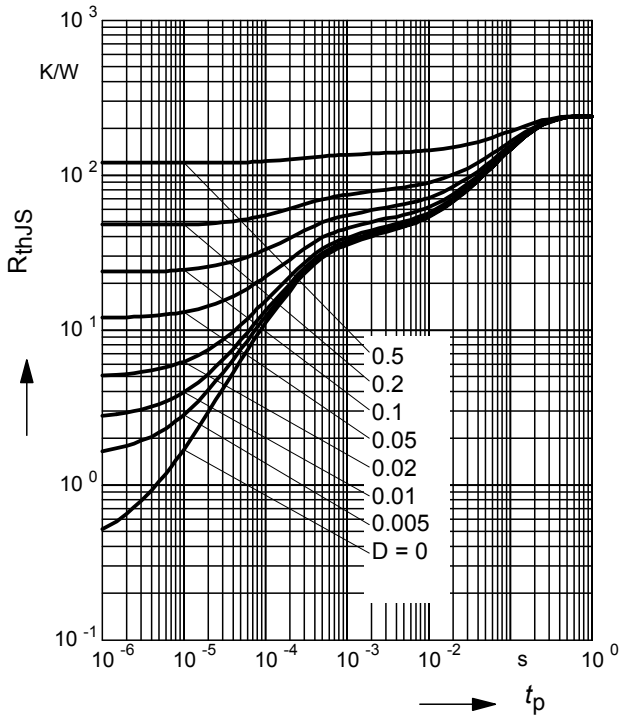
Total power dissipation  $P_{\text{tot}} = f(T_S)$

BCR141W



**Permissible Pulse Load  $R_{thJS} = f(t_p)$**

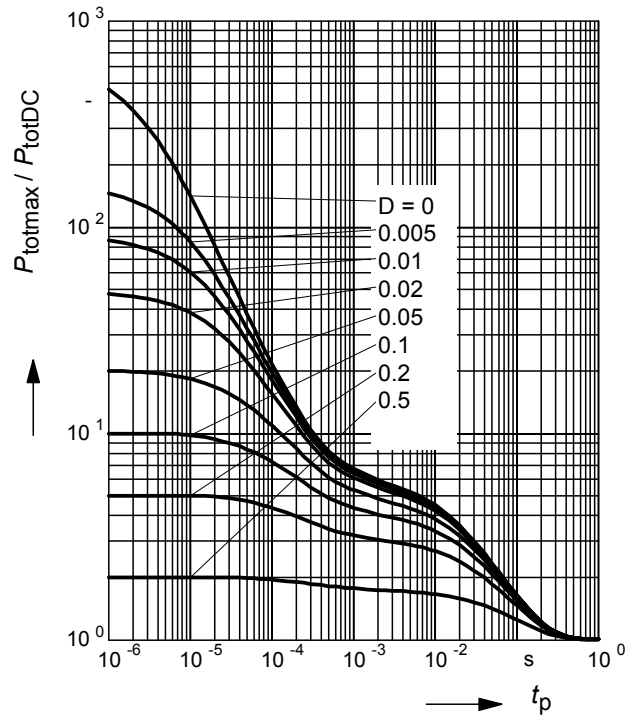
BCR141



**Permissible Pulse Load**

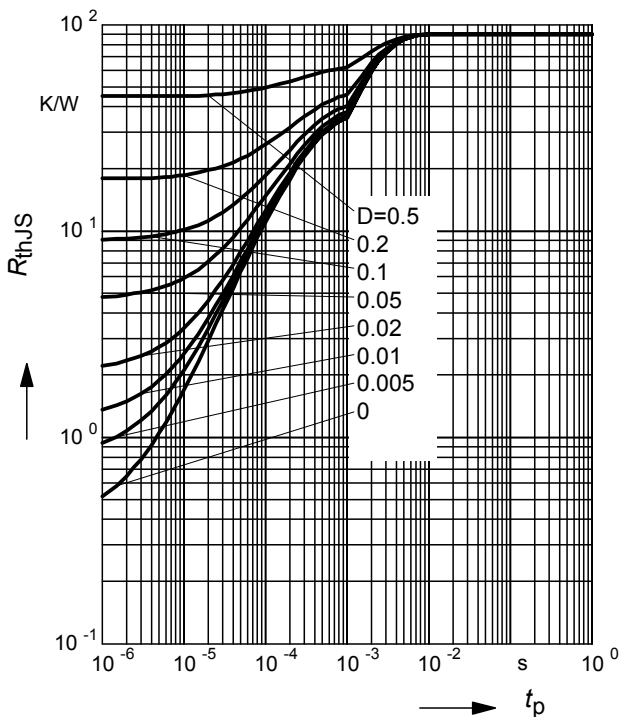
$P_{totmax}/P_{totDC} = f(t_p)$

BCR141



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

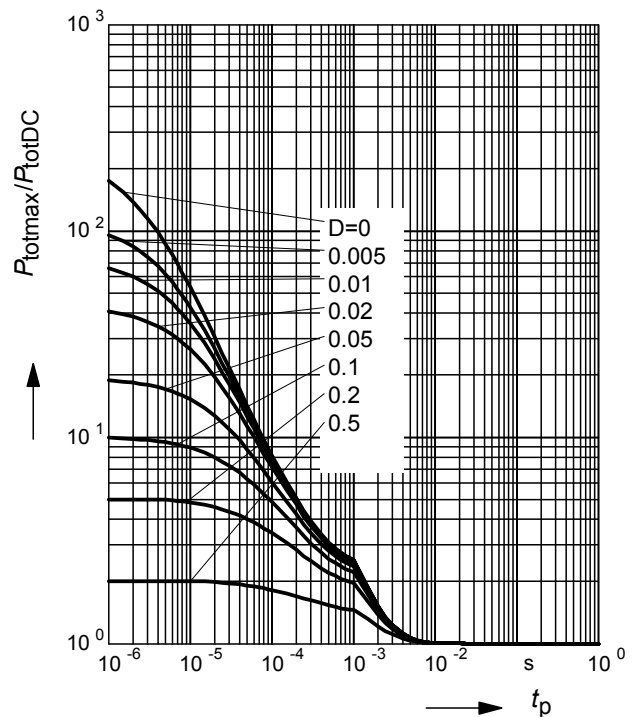
BCR141F



**Permissible Pulse Load**

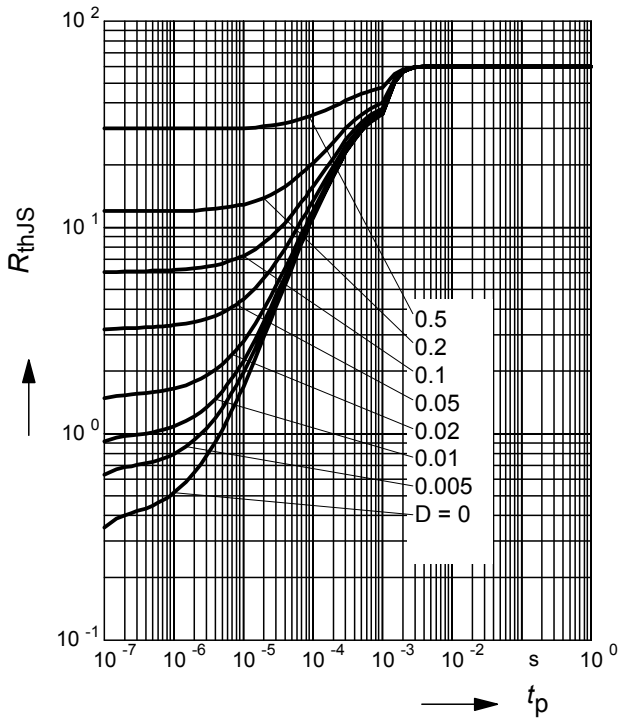
$P_{totmax}/P_{totDC} = f(t_p)$

BCR141F



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

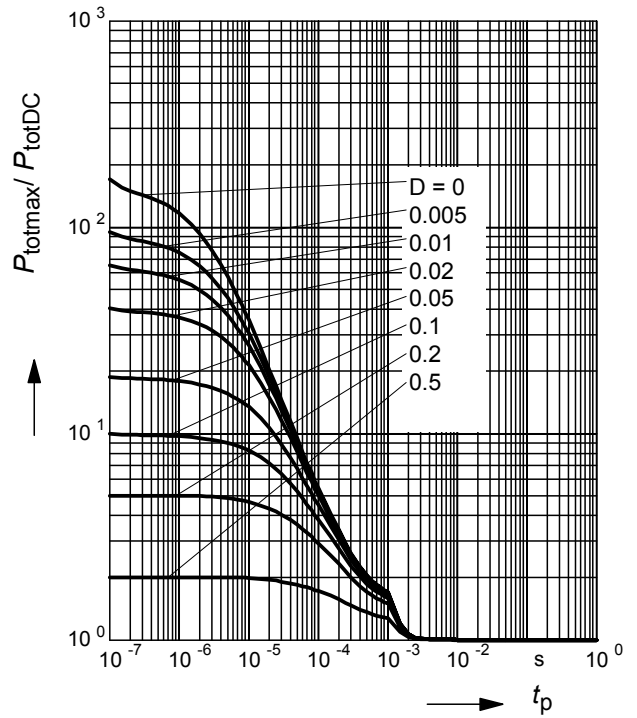
BCR141L3



**Permissible Pulse Load**

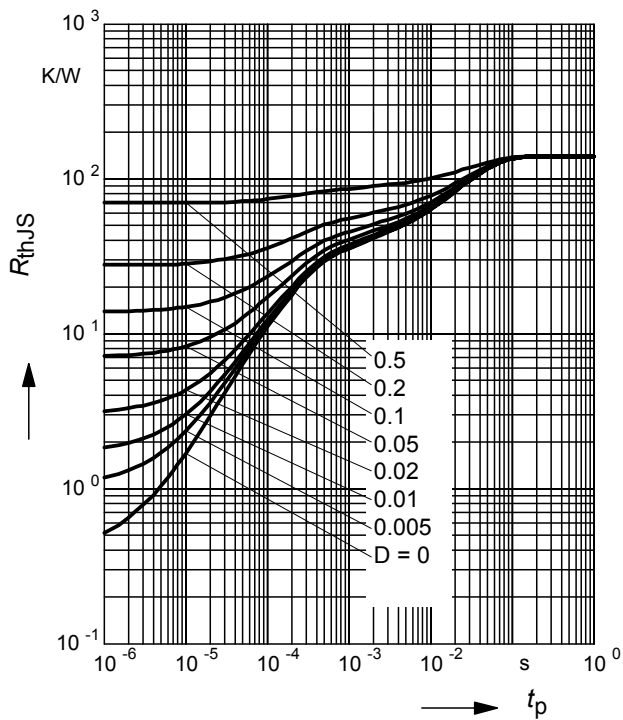
$P_{totmax}/P_{totDC} = f(t_p)$

BCR141L3



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

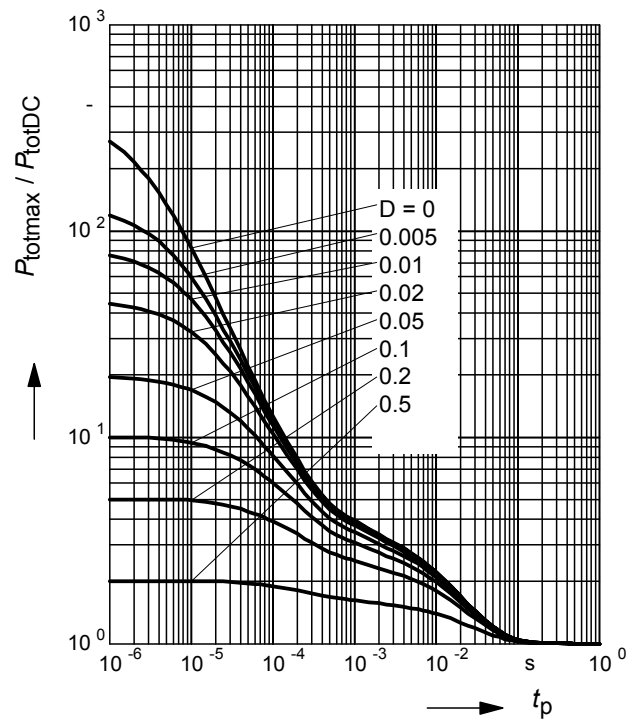
BCR141S



**Permissible Pulse Load**

$P_{totmax}/P_{totDC} = f(t_p)$

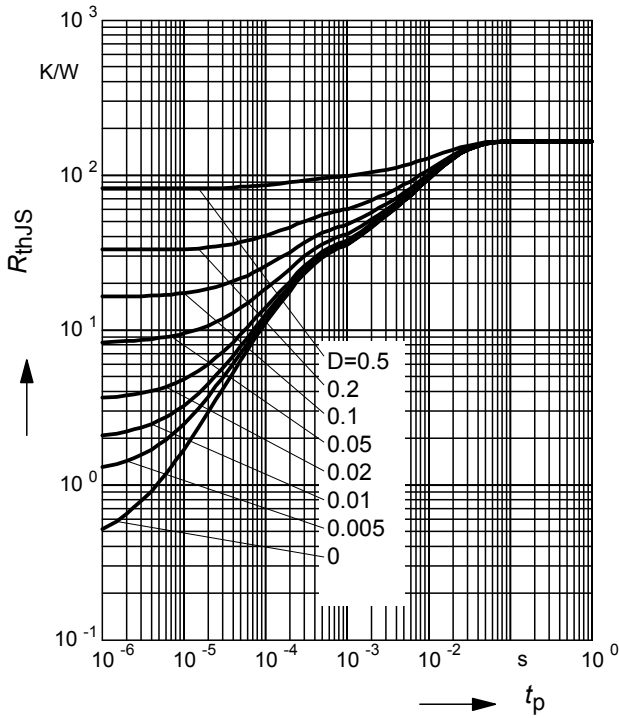
BCR141S





**Permissible Puls Load  $R_{thJS} = f(t_p)$**

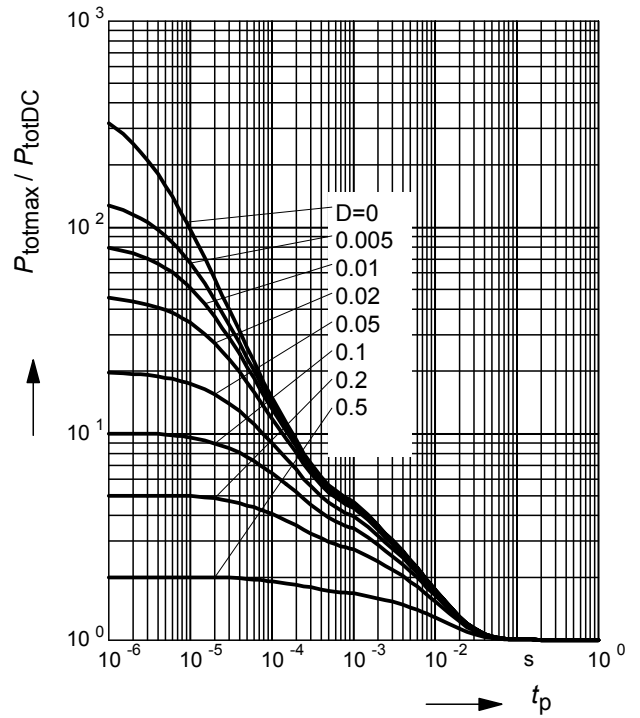
BCR141T



**Permissible Pulse Load**

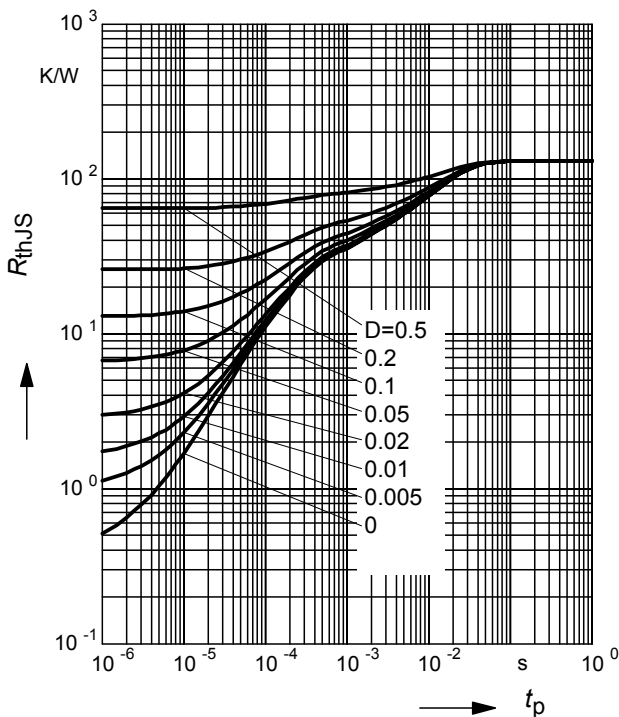
$P_{totmax}/P_{totDC} = f(t_p)$

BCR141T



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

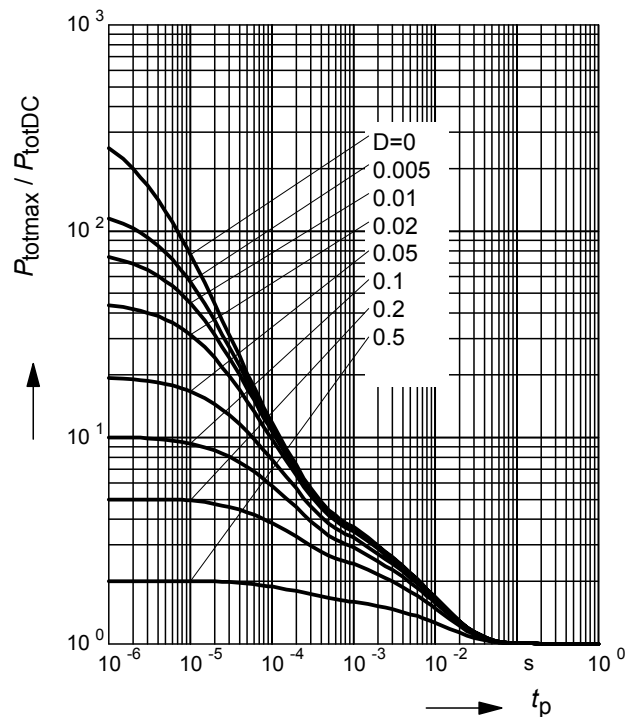
BCR141U



**Permissible Pulse Load**

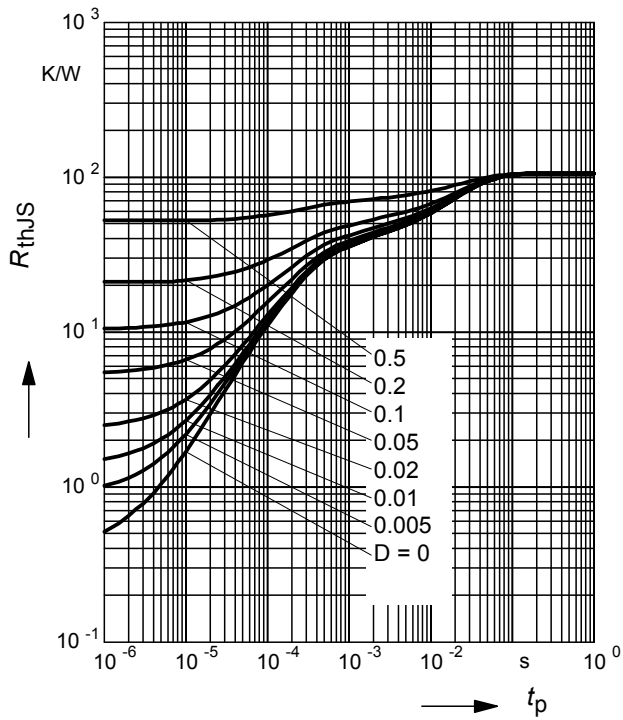
$P_{totmax}/P_{totDC} = f(t_p)$

BCR141U



**Permissible Puls Load  $R_{thJS} = f(t_p)$**

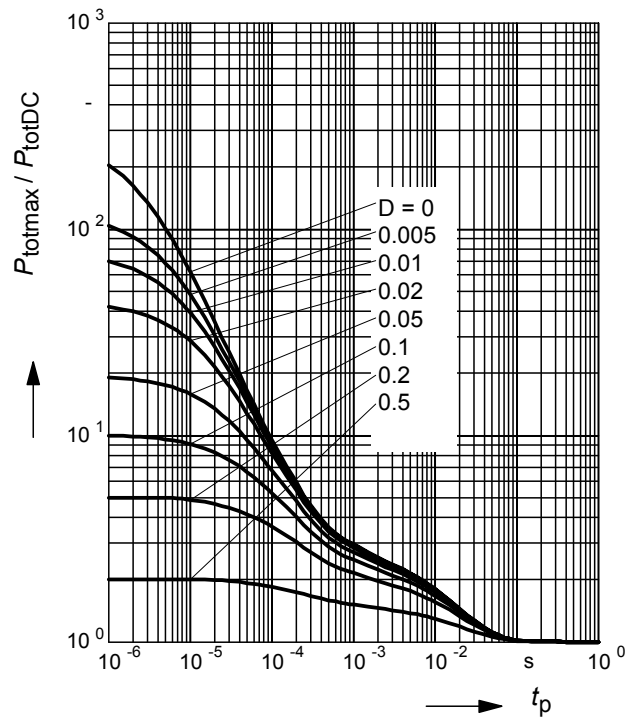
BCR141W



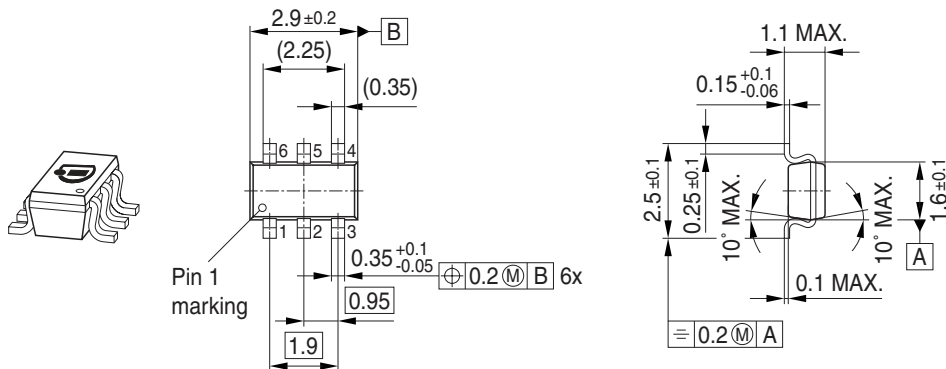
**Permissible Pulse Load**

$P_{totmax}/P_{totDC} = f(t_p)$

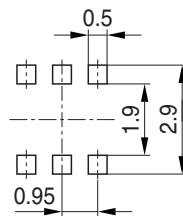
BCR141W



Package Outline

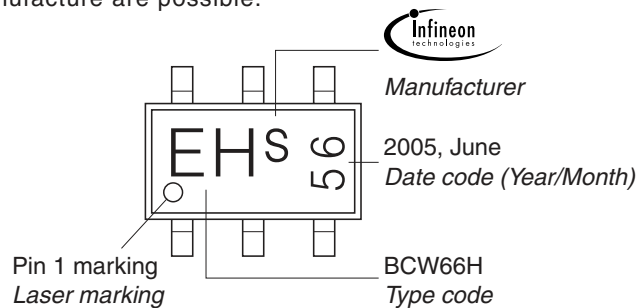


Foot Print



Marking Layout (Example)

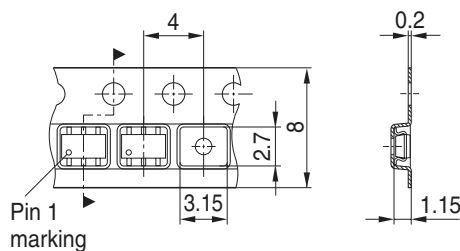
Small variations in positioning of Date code, Type code and Manufacture are possible.



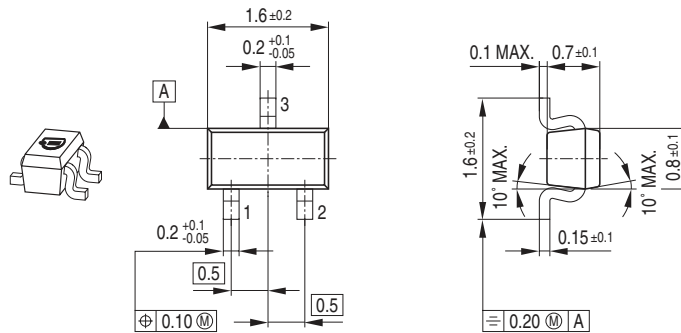
Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

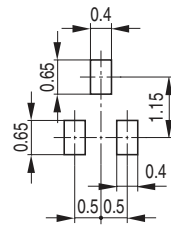
For symmetric types no defined Pin 1 orientation in reel.



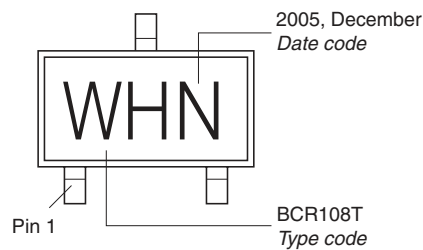
Package Outline



Foot Print

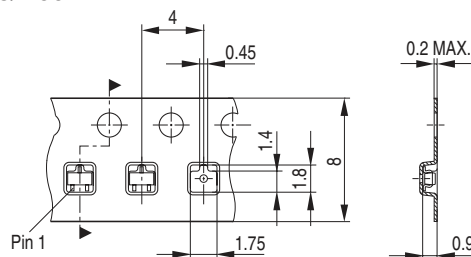


Marking Layout (Example)



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

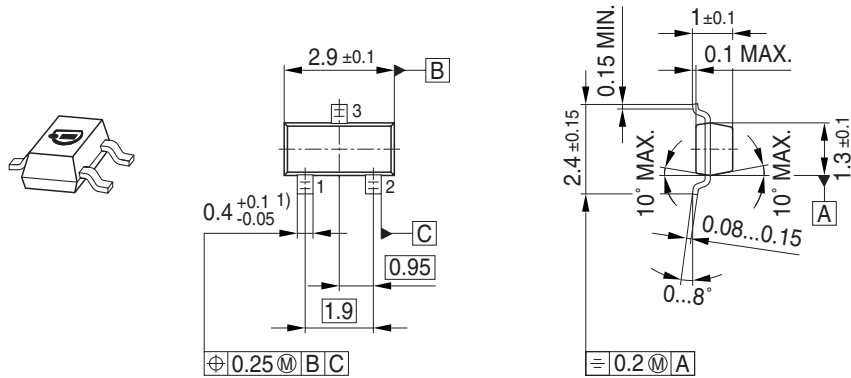


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

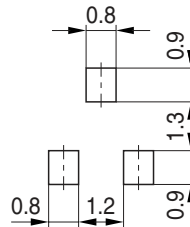
1) New Marking Layout for SC75, implemented at October 2005.

Package Outline

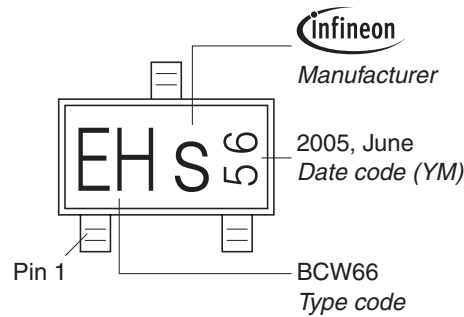


1) Lead width can be 0.6 max. in dambar area

Foot Print

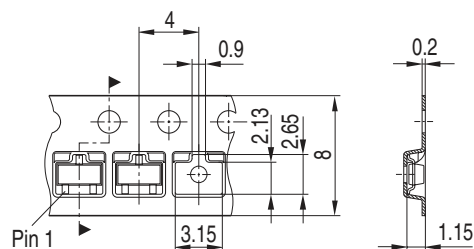


Marking Layout (Example)

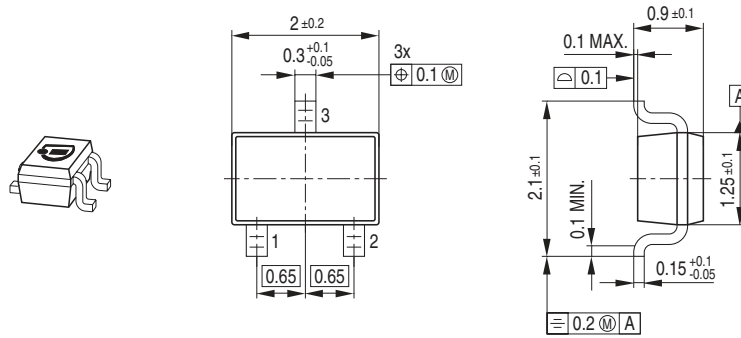


Standard Packing

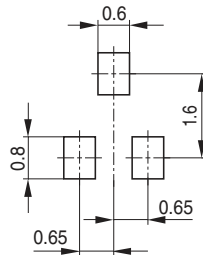
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



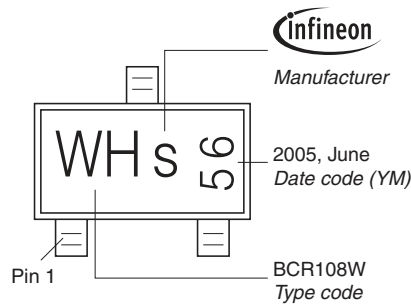
Package Outline



Foot Print

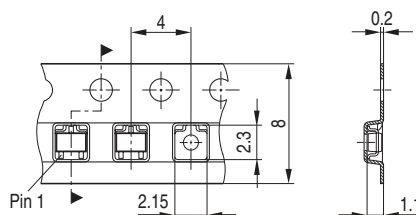


Marking Layout (Example)

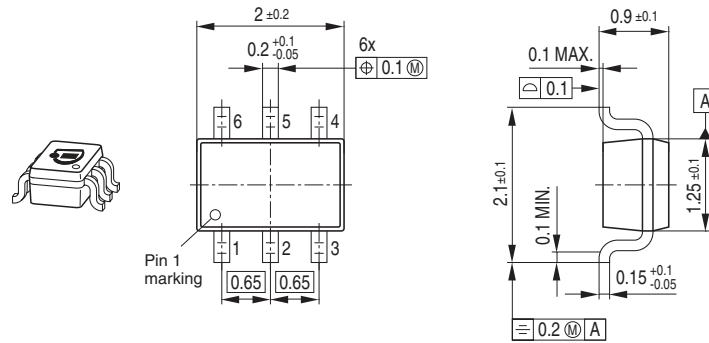


Standard Packing

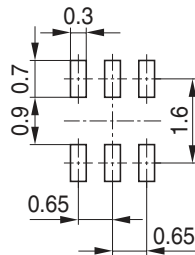
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



Package Outline

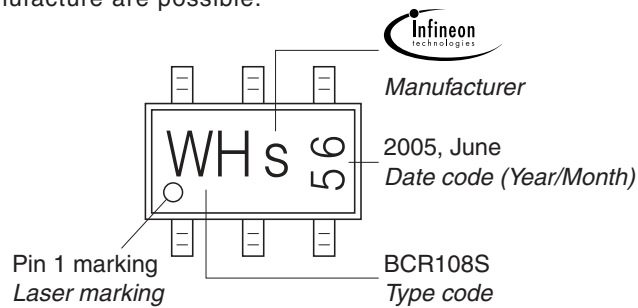


Foot Print



Marking Layout (Example)

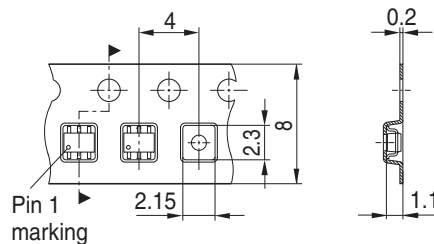
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

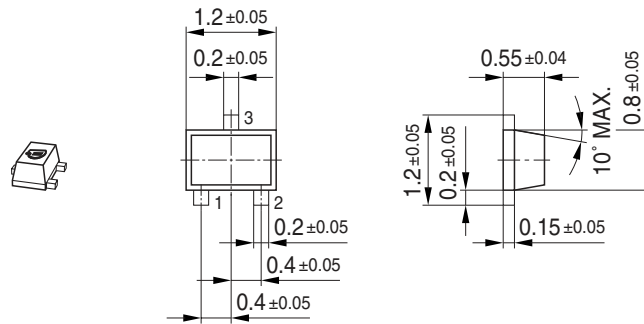
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

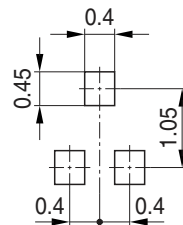




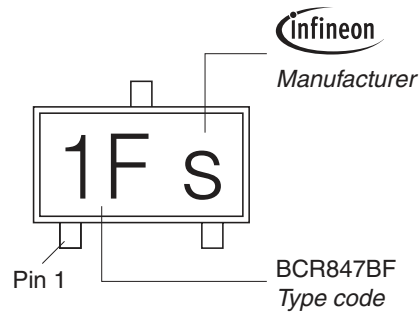
Package Outline



Foot Print

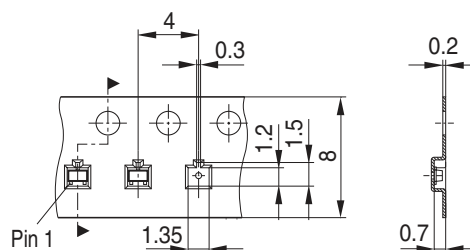


Marking Layout (Example)

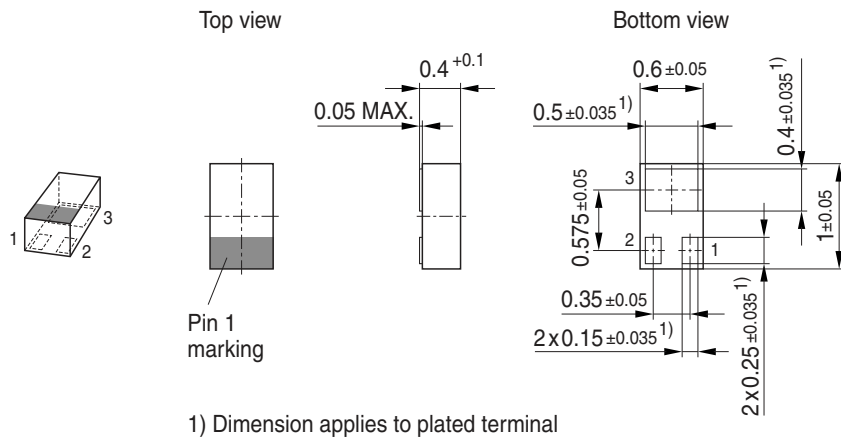


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel

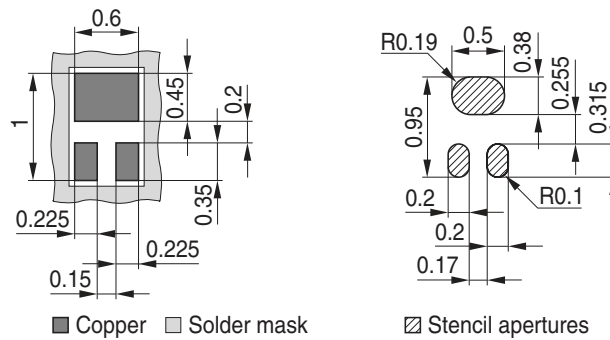


### Package Outline

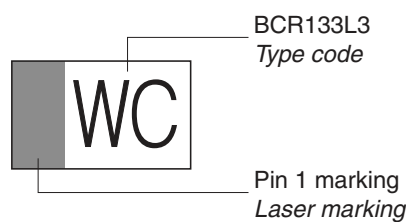


### Foot Print

For board assembly information please refer to Infineon website "Packages"

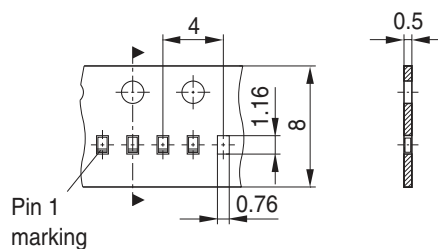


### Marking Layout



### Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.